1. General description

Planar Low V_F Schottky barrier rectifier encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- · Very low forward voltage
- · High power capability due to clip-bonding technology
- · Small and thin SMD plastic package
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- High efficiency DC-to-DC conversion
- · Low voltage rectification
- Switch mode power supply
- · Freewheeling application
- · Reverse polarity protection
- OR-ing

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} \leq 174 °C		-	-	5	A
V_R	reverse voltage	T _j = 25 °C		-	-	60	V
V _F	forward voltage	I _F = 5 A; pulsed; T _j = 25 °C	[1]	-	480	560	mV
I _R	reverse current	$V_R = 60 \text{ V}$; pulsed; $T_j = 25 ^{\circ}\text{C}$	[1]	-	100	400	μA

[1] Very short pulse, in order to maintain a stable junction temperature.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode	5	
2	A	anode		K A
3	K	cathode	2	aaa-009063
			CFP15B (SOT1289B)	

6. Ordering information

Table 3. Ordering information

Type number	Package					
	Name	Description	Version			
PMEG060V050EPE-Q		plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	<u>SOT1289B</u>			

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG060V050EPE-Q	060V 050E

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _R	reverse voltage	T _j = 25 °C		-	60	V
I _F	forward current	δ = 1; $T_{sp} \le 173 ^{\circ}\text{C}$		-	7	А
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 174 °C		-	5	А
I _{FSM}	non-repetitive peak forward current	half sine-wave pulse; t_p = 8.3 ms; $T_{j(init)}$ = 25 °C		-	160	А
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	1.66	W
			[2]	-	2.15	W
Tj	junction temperature			-	175	°C
T _{amb}	ambient temperature			-55	175	°C
T _{stg}	storage temperature			-65	175	°C

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

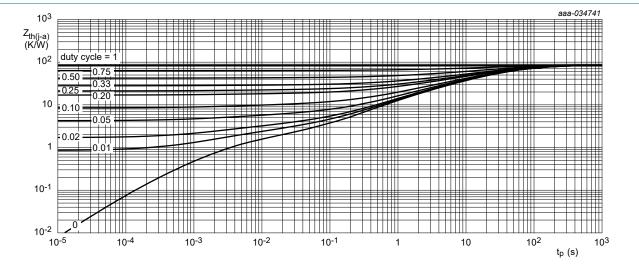
Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

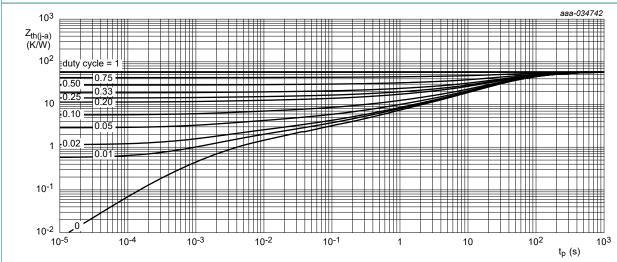
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R _{th(j-a)} thermal resistance from junction to ambient	in free air	[1] [2]	-	-	90	K/W	
		[1] [3]	-	-	70	K/W	
R _{th(j-sp)}	thermal resistance from junction to solder point		[4]	-	-	3	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

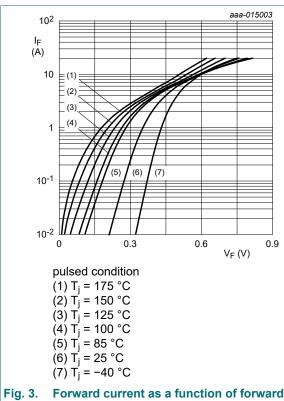
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

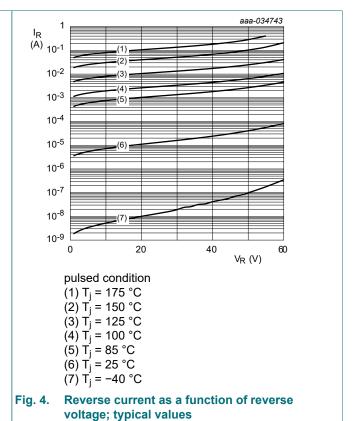
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _{(BR)R}	reverse breakdown voltage	$I_R = 5 \text{ mA}$; pulsed; $T_j = 25 \text{ °C}$	[1]	60	-	-	V
V _F	forward voltage	I _F = 1 A; pulsed; T _j = 25 °C	[1]	-	350	400	mV
		I _F = 5 A; pulsed; T _j = 25 °C	[1]	-	480	560	mV
		I _F = 5 A; pulsed; T _j = -40 °C	[1]	-	530	620	mV
		I _F = 5 A; pulsed; T _j = 125 °C	[1]	-	445	540	mV
I _R	reverse current	V _R = 60 V; pulsed; T _j = 25 °C	[1]	-	100	400	μΑ
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C		-	429	-	pF
		V _R = 10 V; f = 1 MHz; T _j = 25 °C		-	148	-	pF
t _{rr}	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$ $T_j = 25 \text{ °C}$		-	14	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 100 \text{ A/}\mu\text{s}; I_F = 3 \text{ A}; V_R = 30 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$		-	12	-	ns
V_{FRM}	peak forward recovery voltage	$I_F = 0.5 \text{ A}; \text{ d}I_F/\text{d}t = 20 \text{ A/}\mu\text{s}; T_j = 25 °C$		-	340	-	mV

[1] Very short pulse, in order to maintain a stable junction temperature.



g. 3. Forward current as a function of forward voltage; typical values



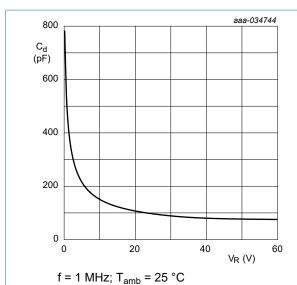
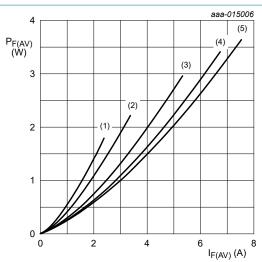
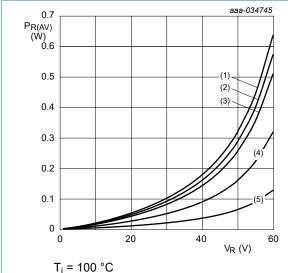


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



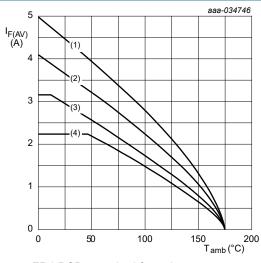
 $T_j = 100 \text{ °C}$ $(1) \delta = 0.1$ $(2) \delta = 0.2$ $(3) \delta = 0.5$ $(4) \delta = 0.8$ $(5) \delta = 1$

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



 $(1) \delta = 1$ $(2) \delta = 0.9$ $(3) \delta = 0.8$ $(4) \delta = 0.5$ $(5) \delta = 0.2$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

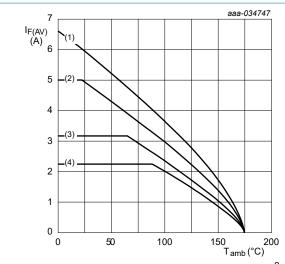
 $T_j = 175 \,^{\circ}\text{C}$ (1) $\delta = 1$; DC

(2) δ = 0.5; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²

 $T_i = 175 \,{}^{\circ}\text{C}$

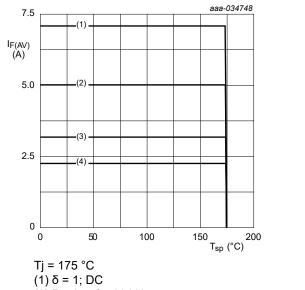
 $(1) \delta = 1; DC$

 $(2) \delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

 $(4) \delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values

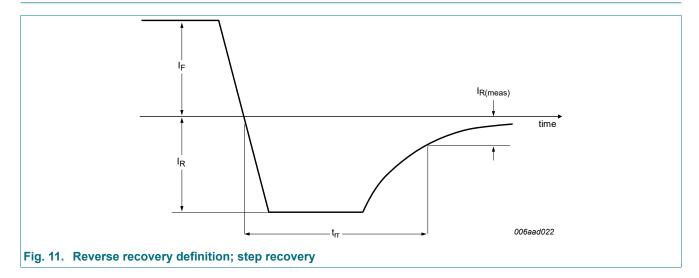


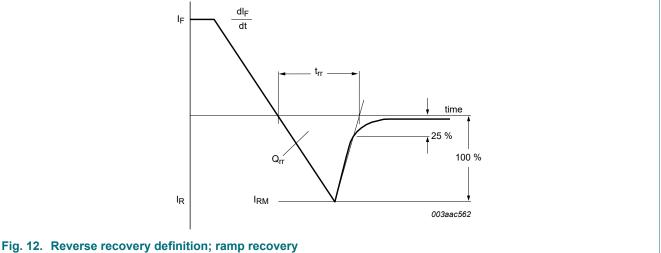
(2) $\delta = 0.5$; f = 20 kHz(3) $\delta = 0.2$; f = 20 kHz

 $(4) \delta = 0.1$; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

11. Test information





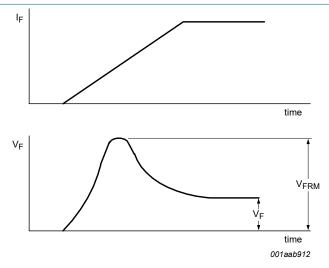


Fig. 13. Forward recovery definition

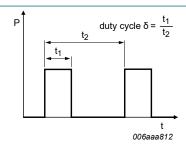


Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

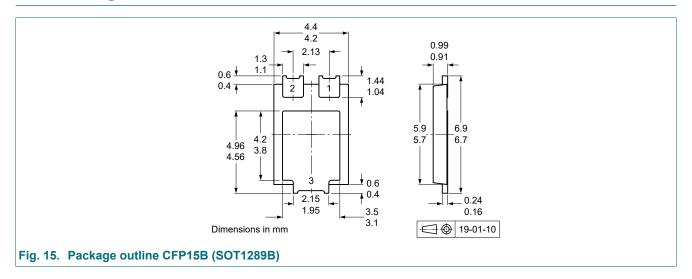
 $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$

with $I_{\mbox{\scriptsize RMS}}$ defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline



13. Soldering

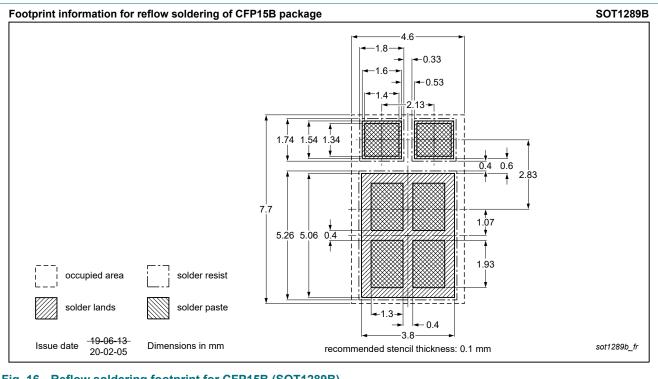


Fig. 16. Reflow soldering footprint for CFP15B (SOT1289B)

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14. Revision history

Table 8. Revision history

Data sheet ID	Release date		Change notice	Supersedes
PMEG060V050EPE-Q v.1	20220719	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
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